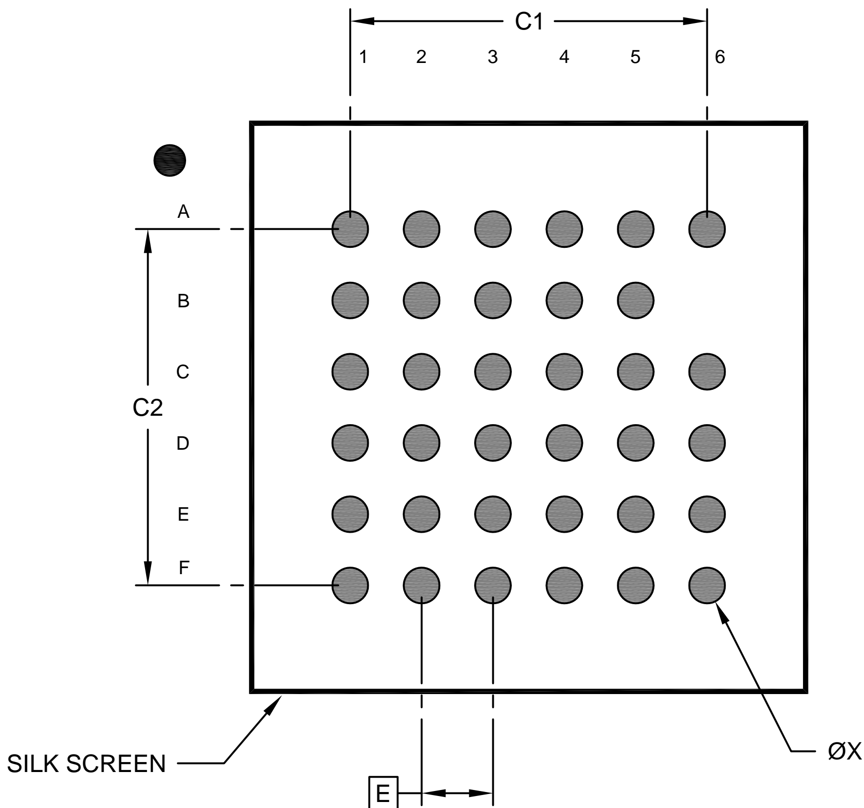
35-Ball Wafer Level Chipscale Package (GUB) - 2.916x2.831 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Contact Pad Spacing	C1		2.00	
Contact Pad Spacing	C2		2.00	
Contact Pad Diameter (X35)	X			0.20

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.